**PACKAGING & ASSEMBLY**

**Manual Wire Bonder**

Manufacturer: Kulike & Soffa  
Model: K&S 4526

**General Description:**

With the manual wire bonder, contacts can be established between chip bond pads and adjacent contact pads, e.g. from a housing in which the chip has been placed or from a printed circuit board on which the chip has been fixed onto. The machine can be equipped with different bonding wires like aluminum, gold or platinum.

**Key Specifications:**

- Default bonding wire: 25µm Aluminum
- Bondhead linear Z travel: 60mm
- Manipulator in X and Y: 18x18mm
- Various mounting options for sample holder. Usually with mechanical clamping or vacuum
- Substrate Size: up to 4 inch
- Heated chuck allows for bonding procedures at elevated temperatures

<table>
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<tr>
<th>Availability</th>
<th>Use allowed for all researchers with permission</th>
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| Location       | Cleanroom C8  
Europastraße 12  
9524 Villach |
| Responsibilities / Contact | Dr. Jochen Bardong / Dr. Ali Roshanghias  
Tel.:+43 4242 56300 209 / 256 |